

Nittobo Joins the HDP (High Density Packaging) User Group, a Global Consortium for Electronic Materials and Packaging Technologies

Nittobo has joined the HDP (High Density Packaging) User Group, a globally recognized consortium advancing high-speed interconnect and packaging technologies. HDP conducts numerous innovative, member-driven projects focused on signal integrity in high-layer count printed wiring boards and high-density packaging technologies, with many leading printed circuit board material manufacturers from Europe, the United States, and Asia participating.



Nittobo joined the HDP (High Density Packaging) User Group to gain early insight into the latest technological trends and shared industry challenges alongside leading global players, and to accelerate the development and evaluation of next-generation materials. This membership comes amid growing global demand for lower-dielectric PCB materials for communications infrastructure and other applications, improved signal integrity in high-speed transmission, and the establishment of globally accepted evaluation and measurement methods, driven by the rapid adoption of generative AI and advances in high-speed communications.

Going forward, through our participation in HDP, we will leverage our expertise in high-performance glass fiber technologies, including NE Glass and NER Glass with outstanding low-dielectric properties and T Glass with low thermal expansion, in consortium projects and contribute to solving challenges facing the next-generation electronics industry. By strengthening co-creation with leading global companies and collaboration across the supply chain, we will accelerate the deployment of products for the advanced semiconductor and AI infrastructure markets, while pursuing sustainable growth in our Electronic Materials Business and enhancing corporate value.



Nittobo's NER glass

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